Status Barrel EMC of the



Target Spectrometer



Federal Ministry of Education and Research

HIC for FAIR

Markus W. H. Moritz

2nd Physics Institute, Giessen University, Germany

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Status Overview

Envisaged milestone (M8): Assembly of 1st full Barrel EMC slice

- Infrastructure
- Mechanics
- 710 detectors
 - 710 crystals in 11 different geometries ✓
 - 1420 APDS
 - Screening including irradiation ✓
 - Matching
 - Glueing
 - Capsules
 - Wrapping
 - Assembly of 18 modules
- Assembly of Supermodules
 - 360 left and 360 right handed APFEL-ASIC with flex PCBs
 - ASIC housing or fixtures
- Assembly of full 1st slice
 - (Re-)design supportbeam
 - Mod. preseries supportbeam
 - Cooling & thermal insulation
 - Backplanes
 - Light pulser fiber coupling











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Х

in progress

in progress

in progress

Support Beam – 1st Design Prototype - Reminder

- Thermal insulation difficult
- Routing FlexPCBs difficult, some can not connected to backplanes

Support beam modification / redesign necessary







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all FlexPCBs can be connected to the backplanes

straight FlexPCB routing possible

full mock up of final design

Pre-Series Supportbeam Remedi

- Derived from final series design: additional threads & cable feed-throughs

Pre-Series Supportbeam Remedi



Backplane Adapters

- Trapezoid shape causes space problems
 stack backplane adapters
- All adapters for full barrel produced
 - Mounting with dummy back-plane sandwiches
 - Optimum APFEL FlexPCB lengths for
 - pre-series slice & series slices will be measured



full mock up of final design







March 10th 2021

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Slice Transportation & Storage

- Limited storage space @ Giessen
 - Max 3 slices
- Storage in Weiterstadt until barrel assembly
 - Up to 4 years for the first slices
- Box specification:
 - Sealing against dust & humidity
 - Mechanical protection (transportation & storage)
 - Lashing points
 - Usable with fork lifter





Slice Transportation & Storage



Slice Transportation & Storage



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Backplanes - Reminder

3 Layers

- Top: HV distribution & regulation
 - Adjust bias voltage of 8 APDs
 - 50V from HV input downwards in < 0,1V steps
 - All channels fed from the same HV source \rightarrow safes space inside support beam
 - Online measurement of APD voltage and current
- Middle: Connector board for signal cables Vsource
- Bottom: Board for FlexPCBs / ASICS
 - Connectors to FEs
 - 8x2 Diff. Line drivers
 - **APFEL I/F buffers**
 - Temp/Humidity sensors



HV distribution prototype

N-Mosfe

APD

- Final Prototype produced in late 2020
 Some minor bugs discovered and fixed
 - Final version can be ordered
- Slow Control Interface and software is under rework
- Calibration and test environment for mass production build up this year
- Most active components have been purchased
- Mass production of the SerialAdapter ASICs got delayed



Crystal Production Status



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Mechanics

- Modification of pre-series support beam done
- All backplane adapters produced
- Backplane test assembly soon (pre-series & series slice)

Slice transportation & storage

- Slices have to be stored in Weiterstadt temporarily
- Rigid and tight boxes for each slice foreseen

• HV backplane

- Design & test processes finished
- Mass production can start

Crystal status

• More than 50% of the crystals for 3rd slice available